

# Using the TPS65000EVM 2.25 MHz Step-Down Converter with Dual LDO

The TPS65000 is a single chip Power Management ICs for portable applications. The device combines a single step-down converter with two low dropout regulators. The step-down converter enters a low power mode at light load for maximum efficiency across the widest possible range of load currents. For low noise applications the device can be forced into fixed frequency PWM mode. The step-down converter allows the use of a small inductor and capacitors to achieve a small solution size. The step-down converter has Power Good status output that can be used for sequencing. The LDOs are capable of supplying 300mA and can operate with an input voltage range between 1.6V and 6.0V, allowing them to be supplied from the step-down converter or directly from the main battery. The step-down converter and the LDOs have separate voltage inputs and enables, allowing for design and sequencing flexibility.

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### 1 Introduction

Introduction

### 1.1 Applications

- Point of Load
- Embedded Processor Power
- Cell Phones, Smart-phones
- PDAs, Pocket PCs
- Portable Media Players

### 1.2 Features

- Input Voltage Rating : 2.3-V up to 6.0-V
- Output Voltages of DCDC converter and LDOs externally adjustable
- Output Current Rating 600-mA (DCDC converter) / 300-mA (LDOs)
- Spread Spectrum Clock (SSC) for best EMI performance
- 2.25-MHz Switching Frequency
- 16 pin 3mm × 3mm QFN package



## 2 TPS65000 EVM Electrical Performance Specifications

PARAMETER		NOTES AND CONDITIONS		MIN	NOM	MAX	UNITS
INPUT CH	ARACTERISTICS						
V <sub>IN</sub>	Input Voltage			3.3		6.0	V
$V_{\text{IN}_{\text{UVLO}}}$	lagest LIV/LO	VIN falling		1.72	1.77	1.82	V
Hyseresis	- Input UVLO				160		mV
OUTPUT C	HARACTERISTICS						
V <sub>ODC</sub>	Output Voltage DCDC	V <sub>IN</sub> = Nom, I <sub>OUT</sub> = Nom			1.2		V
	Accuracy DCDC1	VINDCDC 2.3V to 6V, With 1% tolerance resistores	PFM/PWM	-3.5%		3.5%	
			PWM		3%		
		V <sub>IN</sub> DCDC = 2.3 V to 2.5 V				300	0
OUTDC	Output Current DCDC	V <sub>IN</sub> DCDC = 2.5 V to 6 V				600	mA
VLDO1	Output Voltage LDO1	V <sub>IN</sub> = Nom, I <sub>OUT</sub> = Nom			1.8		V
I <sub>OUTLDO1</sub>	Output Current LDO1	Contentious output current	Contentious output current			300	mA
VLDO2	Output Voltage LDO2				2.8		V
I <sub>OUTLDO2</sub>	Output Current LDO2	Contentious output current				300	mA
	Accuracy LDOs	VINLDO = 1.6 V to 6 V, lout = 1 mA to 175 mA, VLDOx = 1.2 V, With 1% tolerance resistors		-5.5%		5.5%	
		VINLDO = 1.5 V to 6 V, lout = 1 mA to 300 mA, VLDOx = 1.2 V, With 1% tolerance resistors		-5.5%		5.5%	
SYSTEMS	CHARACTERISTICS						
F <sub>SW</sub>	Switching Frequency			1722	2250	2847	kHz

## Table 1. TPS65000EVM Electrical and Performance Specifications

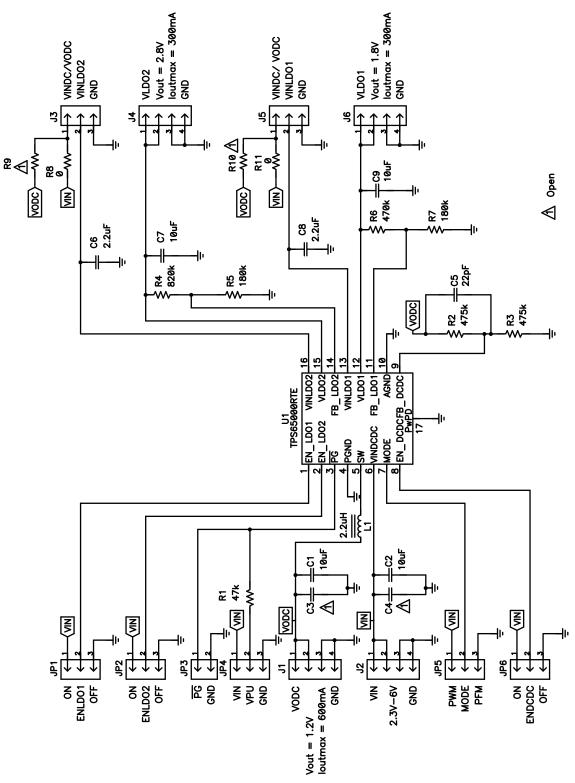


Figure 1. TPS65000EVM Schematic

#### SLVU293–August 2009 Submit Documentation Feedback

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Schematic

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4



#### 4 Connector and Test Point Description

#### 4.1 JP1 – ENLDO1

Placing a shorting bar between ENLDO1 and ON ties the EN pin of LDO1 to VIN, thereby enabling LDO1. Placing a shorting bar between ENLDO1 and OFF ties the EN pin of LDO1 to GND, thereby disabling LDO1

#### 4.2 JP2 – ENLDO2

Placing a shorting bar between ENLDO2 and ON ties the EN pin of LDO2 to VIN, thereby enabling LDO2. Placing a shorting bar between ENLDO2 and OFF ties the EN pin of LDO2 to GND, thereby disabling LDO2

## 4.3 JP3 – PG

JP3 is pulled to GND if the output voltages of the DCDC converter and both LDOs are > 90% of their set point and all enable pins are pulled high.

JP3 pulled up to the selected pull-up voltage level if any of the output voltages VODC, VLDO1 or VLDO2 is <90% of its set point or all enable pins are pulled low

### 4.4 JP4 –VPU

JP4 select the pull-up voltage used for the  $\overline{PG}$  output.

Placing a shorting bar between VPU and VIN select VIN as pull-up voltage. Any other pull-up voltage can be used by removing the shorting bar and connecting a power supply between VPU and GND.

#### 4.5 JP5 – MODE

JP3 selects the forced PWM or Power Save Mode (PSM) operation for the DCDC converter. Placing a shorting bar between MODE and PWM ties the MODE pin of TPS65000 to VIN, thereby selecting forced PWM operating mode for the DCDC converter. Placing a shorting bar between MODE and PFM ties the MODE pin of TPS65000 to GND, thereby selecting Power Save Mode operating mode for the DCDC converter at light-load conditions. If Power Save Mode is selected the DCDC converter will automatically switch to PWM mode at heavier load conditions.

#### 4.6 JP6 – ENDCDC

Placing a shorting bar between ENDCDC and ON ties the EN pin of the DCDC converter to VIN, thereby enabling the DCDC converter. Placing a shorting bar between ENDCDC and OFF ties the EN pin of the DCDC converter to GND, thereby disabling the DCDC converter.

#### 4.7 J1 – VODC/GND

This header is the output of the step-down converter. This output voltage is externally adjustable for the TPS65000. The default setting on the EVM is 1.2V. VODC is capable of sourcing up to 600-mA. A load can be connected between J1 pins 1 and 2 (positive connection) and J1 pins 3 and 4 (GND).

#### 4.8 J2 – VIN / GND

The input power supply has to be connected to this header. The power supply must be connected between J2 pins 1 and 2 (positive connection) and J2 pins 3 and 4 (GND). The leads to the input supply should be twisted and kept as short as possible. The input voltage has to be between 3.3-V and 6-V.



#### 4.9 J3 – VINLDO2

This header is the input supply for LDO2. Placing a shorting bar between VINLDO2 and VINDC/VODC supplies LDO2 from VIN with R2. It can be also supplied from the output of the converter VODC with R1 (not assembled).

An external power supply can be connected between J3 pin2 (VINLDO2) and pin3 (GND). Note that the resistors R1 and R2 should be removed when supplying the LDO from an external power supply.

#### 4.10 J4 – VLDO2/GND

This header is the output of LDO2. This output voltage is externally adjustable for the TPS65000. The default setting on the EVM is 2.8-V. VLDO2 is capable of sourcing up to 300-mA. A load can be connected between J4 pins 1 & 2 (positive connection) and J4 pins 3 & 4 (GND).

#### 4.11 J5 – VINLDO1

This header is the input supply for LDO1. Placing a shorting bar between VINLDO1 and VINDC/VODC supplies LDO1 from VIN with R11. It can be also supplied from the output of the converter VODC with R10 (not assembled). An external power supply can be connected between J5 pin2 (VINLDO1) and pin3 (GND). Please note that the resistors R10 and R11 should be removed when supplying the LDO from an external power supply.

#### 4.12 J6 – VLDO1/GND

This header is the output of LDO1. This output voltage is externally adjustable for the TPS65000. The default setting on the EVM is 1.8-V. VLDO2 is capable of sourcing up to 300-mA. A load can be connected between J6 pins 1 and 2 (positive connection) and J6 pins 3 and 4 (GND).

## 5 4 TPS65000/1 Typical Performance Data and Characteristic Curves

Figure 2 through Figure 9 present typical performance curves for the TPS65000/1. Since actual performance data can be affected by measurement techniques and environmental variables, these curves are presented for reference and may differ from actual field measurements.

#### 5.1 Efficiency

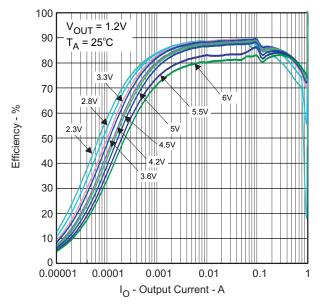


Figure 2. TPS65000/1 Efficiency vs Load Current



### 5.2 Line and Load Regulation

Figure 3 and Figure 4 show the load transient response of the DCDC converter and LDO, while Figure 5 and Figure 6 show the line transient response.

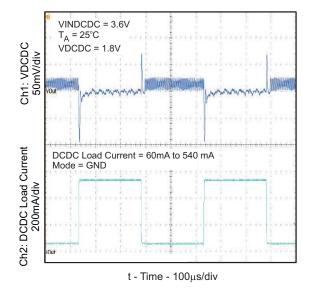


Figure 3. TPS65000/1 DCDC Converter Load Transient Response

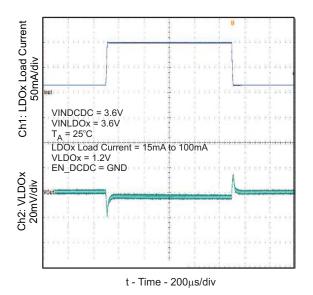


Figure 4. TPS65000/1 LDOx Transient Response



4 TPS65000/1 Typical Performance Data and Characteristic Curves



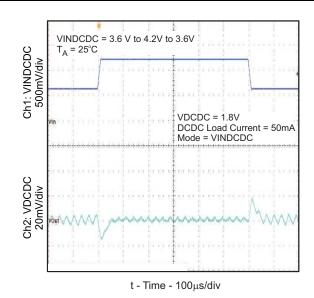


Figure 5. TPS65000/1 DCDC Converter Line Transient Response

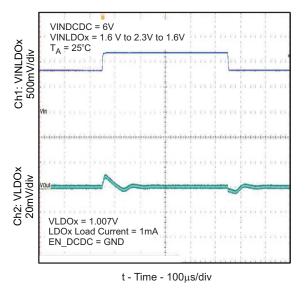


Figure 6. TPS65000/1 LDOx Line Transient Response



## 5.3 Output Voltage Ripple

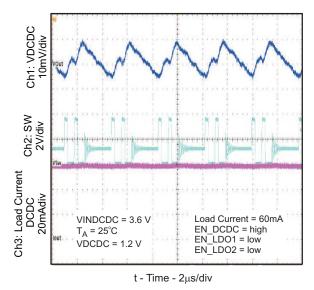


Figure 7. TPS65000/1 Output Voltage Ripple (MODE = low)

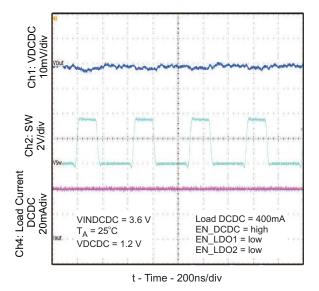


Figure 8. TPS65000/1 Output Voltage Ripple (MODE = high)



4 TPS65000/1 Typical Performance Data and Characteristic Curves

## Startup Timing

5.4

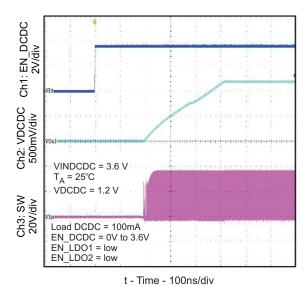


Figure 9. TPS65000/1 DCDC Converter Startup Timing



#### 6 EVM Assembly Drawings and Layout

The following figures (Figure 10 through Figure 12) show the design of the TPS65000EVM printed circuit board. The EVM has been designed using a 2-Layer, 1oz copper-clad circuit board 2.7" x 2.1" (68.6mm x 55.3mm).

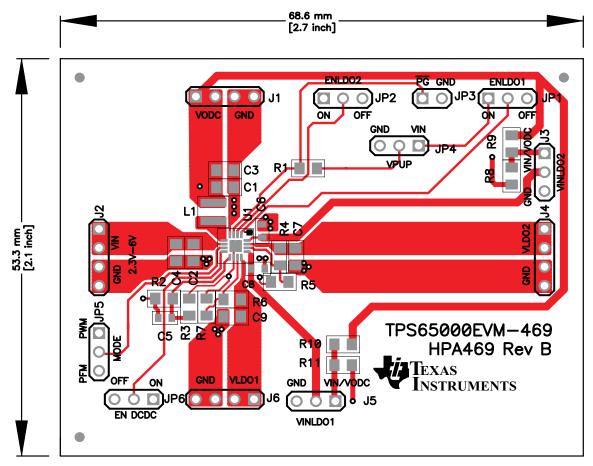


Figure 10. TPS65000EVM Component Placement (Viewed from Top)



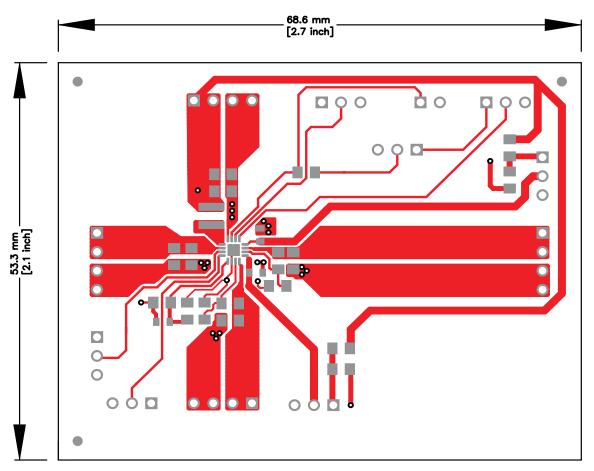


Figure 11. TPS65000EVM Top Copper (Viewed from Top)



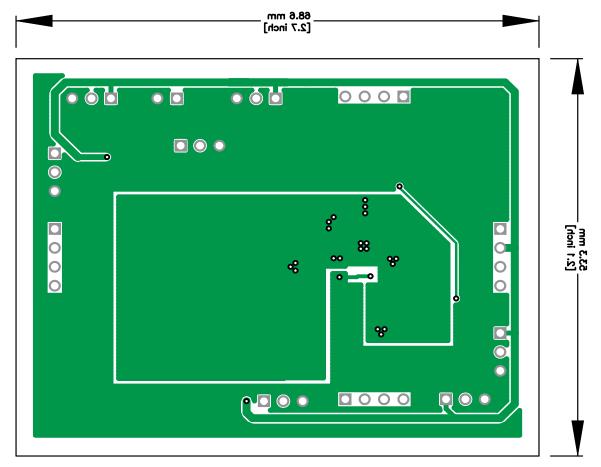


Figure 12. TPS65000EVM Bottom Copper (Viewed from Bottom)



List of Materials

#### 7 **List of Materials**

Table 2 lists the EVM components as configured according to the schematic shown in Figure 1.

Count	RefDes	Value	Description	Size	Part Number	MFR
0	C1, C2	open	Capacitor, Ceramic, 10V, X5R, 10%	0805	GRM21BR61A106KE19L	Murata
4	C3, C4, C7, C9	10 μF	Capacitor, Ceramic, 10V, X5R, 10%	0805	GRM21BR61A106KE19L	Murata
1	C5	22 pF	Capacitor, Ceramic, 50V, COG, 5%	0603	C1608COG1H220J	TDK
2	C6, C8	2.2 μF	Capacitor, Ceramic, 16V, X5R, 10%	0603	GRM188R61C225KE15D	Murata
4	J1, J2, J4, J6		Header, Male 4-pin, 100mil spacing, (36-pin strip)	0.100 inch $\times$ 4	PTC36SAAN	Sullins
2	J3, J5		Header, Male 3-pin, 100mil spacing, (36-pin strip)	0.100 inch $\times$ 3	PTC36SAAN	Sullins
5	JP1, JP2, JP4, JP5, JP6		Header, Male 3-pin, 100mil spacing, (36-pin strip)	0.100 inch × 3	PTC36SAAN	Sullins
1	JP3		Header, Male 2-pin, 100mil spacing, (36-pin strip)	0.100 inch $\times2$	PTC36SAAN	Sullins
1	L1	2.2 μΗ	Inductor, SMT, 2.0A, 110milliohm	$0.118 \times 0.118$ inch	LPS3015-222ML	Coilcraft
1	R1	47k	Resistor, Chip, 1/10W, 1%	0805	Std	Std
2	R2, R3	475k	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R4	820k	Resistor, Chip, 1/10W, 1%	0805	Std	Std
2	R5, R7	180k	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R6	470k	Resistor, Chip, 1/10W, 1%	0805	Std	Std
2	R8, R11	0	Resistor, Chip, 1/10W, 1%	0805	Std	Std
0	R9, R10	open	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	U1	TPS65000RTE	IC, 2.25 MHz Step-Down Converter W/ dual LDO and SVS	QFN-16	TPS65000RTE	TI
1	-		PCB, 2.7 In × 2.1 In × 0.0062 In		HPA469	Any
7	—		Shunt, 100-mil, Black	0.100		Any

#### Table 2. TPS65000EVM Bill of Materials

Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. 2. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2. 3.

4.

Ref designators marked with an asterisk (\*\*\*) cannot be substituted. All other components can be substituted with equivalent MFG's components.

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